

1 Amp. Surface Mounted Very Fast Soft Recovery Glass Passivated Avalanche Diode

Dimensions in mm. CASE: SMA/DO-214AC	Voltage 200 to 600 V. Current 1.0 A at 55 °C. HYPERECTIFIER® • Glass Passivated Junction • High current capability • The plastic material carries U/L 94 V-0 • Low profile package. • Easy pick and place. • High temperature soldering 260 °C 10 sec. MECHANICAL DATA Terminals: Solder plated, solderable per IEC 68-2-20. Standard Packaging: 4 mm. tape (EIA-RS-481). Weight: 0.064 g.
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Maximum Ratings, according to IEC publication No. 134

		FES26A	FES26B	FES26C
Marking Code		E1	E2	E3
V_{RRM}	Peak Recurrent reverse voltage (V)	200	400	600
V_{RMS}	Maximum RMS voltage	140	280	420
V_{DC}	Maximum DC blocking voltage	200	400	600
$I_{F(AV)}$	Forward current at Tamb = 55 °C	1 A		
I_{FRM}	Recurrent peak forward current	10 A		
I_{FSM}	10 ms. peak forward surge current (Jedec Method)	30 A		
t_{rr}	Max. reverse recovery time from $I_F = 0.5 A$; $I_R = 1 A$; $I_{RR} = 0.25 A$	30 ns		
V_{BR}	Avalanche breakdown voltage at 100 μA (V)	>300	>500	>700
T_j	Operating temperature range	– 55 to + 150 °C		
T_{stg}	Storage temperature range	– 55 to + 150 °C		
E_{RSM}	Maximum non repetitive peak reverse avalanche energy. $I_R = 1 A$; $T_1 = 25 °C$	10 mJ		

Electrical Characteristics at Tamb = 25 °C

V_F	Max. forward voltage drop at $I_F = 1 A$	at 25 °C 2.5 V at 150 °C 1.3 V
I_R	Max. reverse current at V_{RRM}	at 25 °C 5 μA at 100 °C 100 μA
R_{thj-l} R_{thj-a}	Typical thermal resistance (5 x 5 mm ² x 130 μm Copper Area)	27 °C/W 75 °C/W

Rating And Characteristic Curves

